

TAIWAN SEMICONDUCTOR MANUFACTURING CO LTD

Form 6-K

October 16, 2014

1934 Act Registration No. 1-14700

SECURITIES AND EXCHANGE COMMISSION

Washington, DC 20549

FORM 6-K

REPORT OF FOREIGN PRIVATE ISSUER

PURSUANT TO RULE 13a-16 OR 15d-16 OF

THE SECURITIES EXCHANGE ACT OF 1934

For the month of October 2014

Taiwan Semiconductor Manufacturing Company Ltd.

(Translation of Registrant's Name Into English)

No. 8, Li-Hsin Rd. 6,

Hsinchu Science Park,

Taiwan

(Address of Principal Executive Offices)

(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F ☒ Form 40-F ☐

(Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.)

Yes ☐ No ☒

(If ☒ Yes is marked, indicated below the file number assigned to the registrant in connection with Rule 12g3-2(b): 82: .)

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Taiwan Semiconductor Manufacturing Company Ltd.

Date: October 16, 2014

By /s/ Lora Ho

Lora Ho

Senior Vice President & Chief Financial Officer

TSMC Reports Third Quarter EPS of NT\$2.94

Hsinchu, Taiwan, R.O.C., Oct. 16, 2014 TSMC today announced consolidated revenue of NT\$209.05 billion, net income of NT\$76.34 billion, and diluted earnings per share of NT\$2.94 (US\$0.49 per ADR unit) for the third quarter ended September 30, 2014.

Year-over-year, third quarter revenue increased 28.6% while net income and diluted EPS both increased 46.9%. Compared to second quarter 2014, third quarter results represent a 14.2% increase in revenue, and a 27.9% increase in net income. All figures were prepared in accordance with TIFRS on a consolidated basis.

In US dollars, third quarter revenue increased 14.7% from the previous quarter and increased 28.1% year-over-year.

Gross margin for the quarter was 50.5%, operating margin was 40.4%, and net profit margin was 36.5%.

Shipments of 20-nanometer process technology accounted for 9% of total wafer revenues. 28-nanometer accounted for 34% of total wafer revenues. Advanced technologies, defined as 28-nanometer and 20-nanometer technologies, accounted for 43% of total wafer revenues.

In the third quarter, TSMC broke new record in revenue thanks to strong demand for TSMC's advanced technologies. After two years of meticulous preparation, we began volume shipments of 20-nanometer wafers, which reached 9 percent of our third quarter wafer revenue, said Lora Ho, SVP and Chief Financial Officer of TSMC. We expect 20-nanometer will continue to ramp up fast and will account for more than 20 percent of our fourth quarter wafer revenue. Based on our current business outlook and exchange rate assumption of 1 US dollar to 30.31 NT dollars, management expects overall performance for fourth quarter 2014 to be as follows:

Revenue is expected to be between NT\$217 billion and NT\$220 billion;

Gross profit margin is expected to be between 48% and 50%;

Operating profit margin is expected to be between 38% and 40%.

TSMC's 2014 third quarter consolidated results:

(Unit: NT\$ million, except for EPS)

	3Q14 Amount ^a	3Q13 Amount	YoY Inc. (Dec.) %	2Q14 Amount	QoQ Inc. (Dec.) %
Net sales	209,049	162,577	28.6	183,021	14.2
Gross profit	105,578	78,891	33.8	91,193	15.8
Income from operations	84,432	59,618	41.6	70,714	19.4
Income before tax	85,381	59,349	43.9	74,098	15.2
Net income	76,335	51,952	46.9	59,702	27.9
EPS (NT\$)	2.94 ^b	2.00 ^c	46.9	2.30 ^b	27.9

*a: 3Q2014 figures have not been approved by Board of Directors**b: Based on 25,930 million weighted average outstanding shares**c: Based on 25,929 million weighted average outstanding shares***About TSMC**

TSMC is the world's largest dedicated semiconductor foundry, providing the industry's leading process technology and the foundry's largest portfolio of process-proven libraries, IPs, design tools and reference flows. The Company's owned capacity in 2014 is expected to be about 8.2 million (12-inch equivalent) wafers, including capacity from three advanced 12-inch GIGAFAB facilities, four eight-inch fabs, one six-inch fab, as well as TSMC's wholly owned subsidiaries, WaferTech and TSMC China. TSMC is the first foundry to provide both 20nm and 16nm production capabilities. Its corporate headquarters are in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

#

TSMC Spokesperson: **TSMC Acting Spokesperson:** **For Further Information:**

Lora Ho	Elizabeth Sun	Michael Kramer	Hui-Chung Su
Senior VP & CFO	Director	Principal Specialist	Administrator
Tel: 886-3-505-4602	Corporate Communication Division	PR Department	PR Department
	Tel: 886-3-568-2085	Tel: 886-3-563-6688	Tel: 886-3-563-6688
	Mobile: 886-988-937-999	Ext. 7126216	Ext. 7125033
		Mobile: 886-988-931-352	Mobile: 886-988-930-039

E-Mail:
elizabeth_sun@tsmc.com

E-Mail:
pdkramer@tsmc.com

E-Mail: hcsuq@tsmc.com